

Product Texts

Zytel® HTNWR51G30 NC010 is a 30% Glass Reinforced, PPA, Teflon® Lubricated, High Performance Polyamide with Low Wear and Low Friction

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.2 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.7 / *	%	ISO 294-4, 2577
^[C] Density of melt	1350	kg/m ³	-
^[C] Thermal conductivity of melt	0.23	W/(m K)	-
^[C] Spec. heat capacity of melt	1740	J/(kg K)	-

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	10000 / 10000	MPa	ISO 527
^[C] Stress at break	190 / 173	MPa	ISO 527
^[C] Strain at break	2.6 / 2.2	%	ISO 527
^[C] Charpy impact strength, +23°C	65 / -	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	11 / -	kJ/m ²	ISO 179/1eA
^[C] Charpy notched impact strength, -30°C	9 / -	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	300 / *	°C	ISO 11357-1/-3
^[C] Glass transition temperature, 10°C/min	135 / *	°C	ISO 11357-1/-2
^[C] Temp. of deflection under load, 1.80 MPa	260 / *	°C	ISO 75-1/-2
^[C] Coeff. of linear therm. expansion, parallel	15 / *	E-6/K	ISO 11359-1/-2
^[C] Coeff. of linear therm. expansion, normal	60 / *	E-6/K	ISO 11359-1/-2

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Comparative tracking index	550 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Density	1560 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics**Processing**

Injection Molding

Delivery form

Pellets

Additives

Lubricants, Release agent

Special Characteristics

Heat stabilized or stable to heat

Features

Tribologic Grade

Regional Availability

North America, South and Central America

Other text information**Injection molding**

During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

When lower mold temperatures are used, the initial warpage and shrinkage may be lower, but the surface appearance and chemical resistance may be reduced, and the dimensional change may be greater when parts are subsequently heated.